

/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V _{DS}	60	V
Continuous Drain Current		I _D (T _c =25 °C)	158	A
Pulsed Drain Current		I _{DM}	316	A
Gate-Source Voltage		V _{GS}	± 20	V
Power Dissipation		P _D (T _c =25 °C)	90	W
Avalanche energy(L=0.5mH)		E _{AS}	380	mJ
Avalanche Current(L=0.5mH)		I _{AS}	30.8	A
Junction and Storage Temperature Range		T _j , T _{stg}	-55 to 150	°C
Maximum Junction-to-Ambient	t ≤ 10s	R _{θJA}	20	W
	Steady-State		57	
Maximum Junction-to-Case	Steady-State	R _{θJC}	1.39	

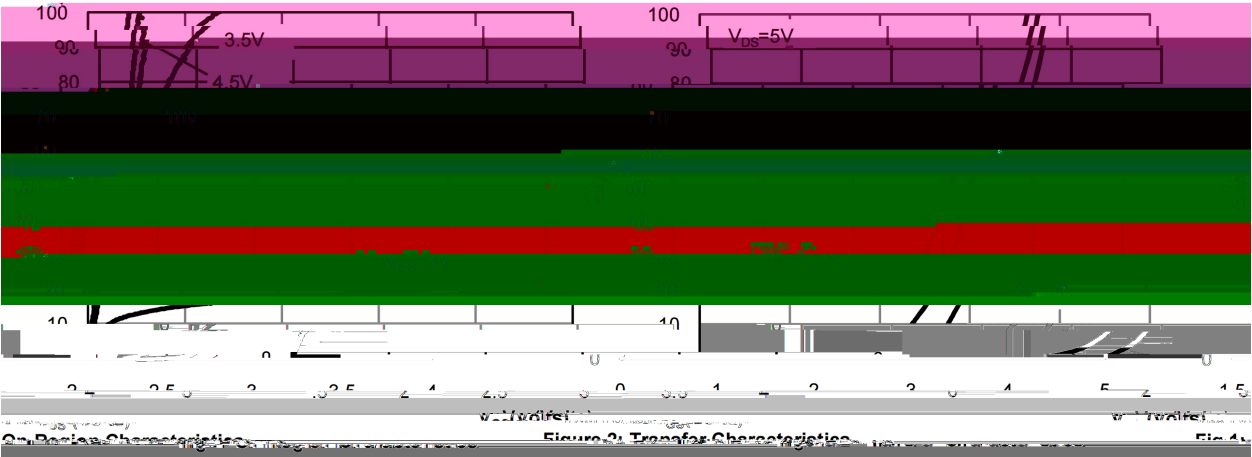
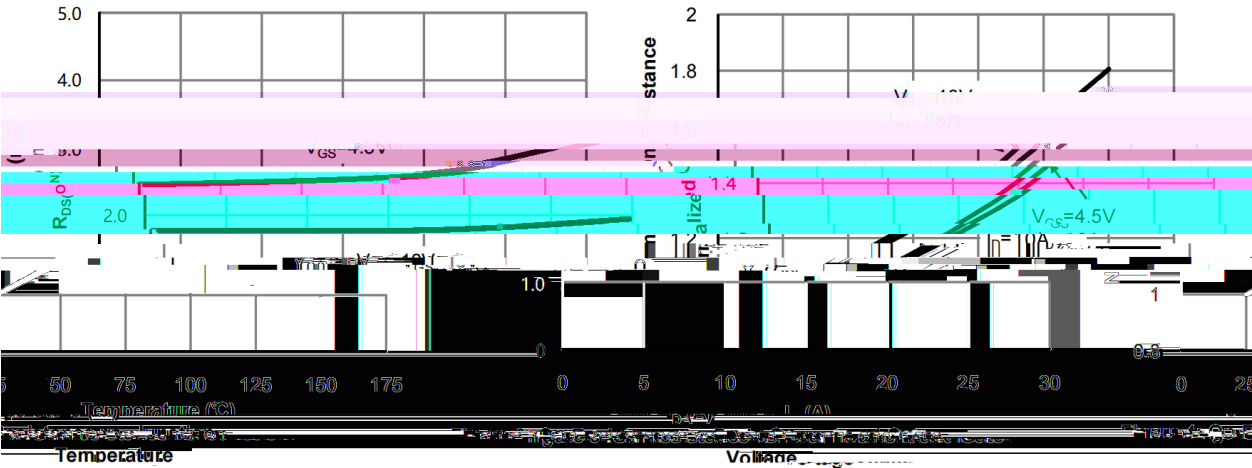
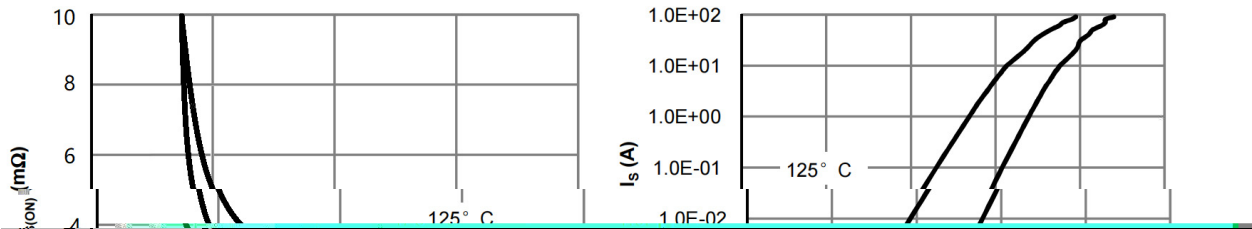
/ Electrical Characteristics($T_a=25^\circ\text{C}$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}$ $I_D=250\mu\text{A}$	60	65		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60\text{V}$ $V_{GS}=0\text{V}$			1	μA
Gate-Body Leakage Current Forward	I_{GSS}	$V_{GS}=\pm 20\text{V}$ $V_{DS}=0\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu\text{A}$	1	1.6	2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}$ $I_D=20\text{A}$		1.8	2.5	m Ω
		$V_{GS}=4.5\text{V}$ $I_D=10\text{A}$		2.4	3.5	
Forward On Voltage	V_{SD}	$V_{GS}=0\text{V}$ $I_S=1\text{A}$			1.2	V
Gate resistance	R_g	$f=1\text{MHz}$		1.0		Ω
Input Capacitance	C_{iss}	$V_{DS}=25\text{V}$ $V_{GS}=0\text{V}$ $f=1.0\text{MHz}$		6700		pF
Output Capacitance	C_{oss}			1400		
Reverse Transfer Capacitance	C_{rss}			70		
Total Gate Charge	$Q_{g(10V)}$	$V_{GS}=10\text{V}$ $V_{DS}=30\text{V}$ $I_D=20\text{A}$		60		nC
Total Gate Charge	$Q_{g(4.5V)}$			23		
Gate Source Charge	Q_{gs}			16		
Gate Drain Charge	Q_{gd}			3		

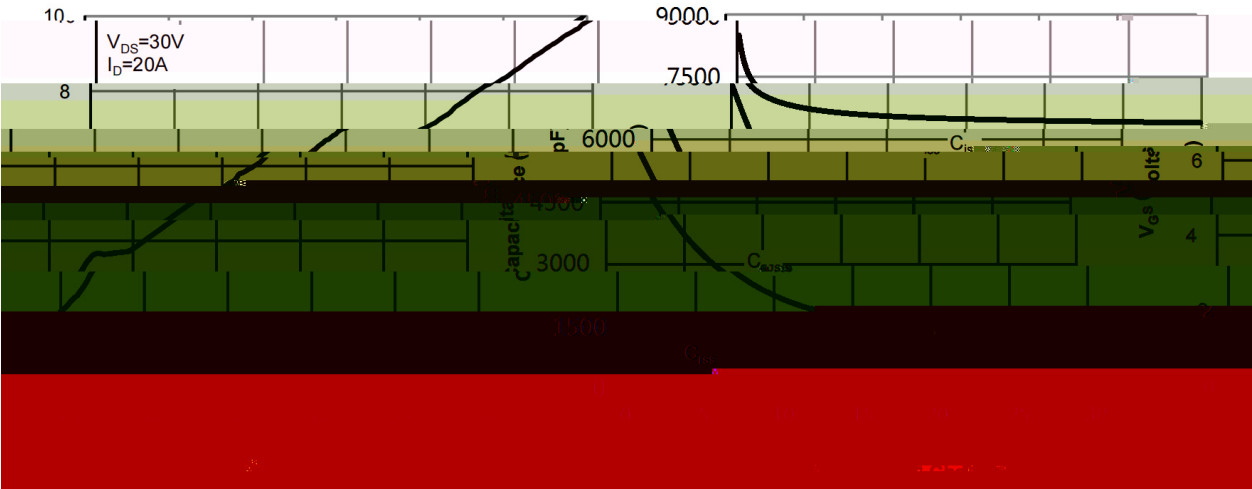
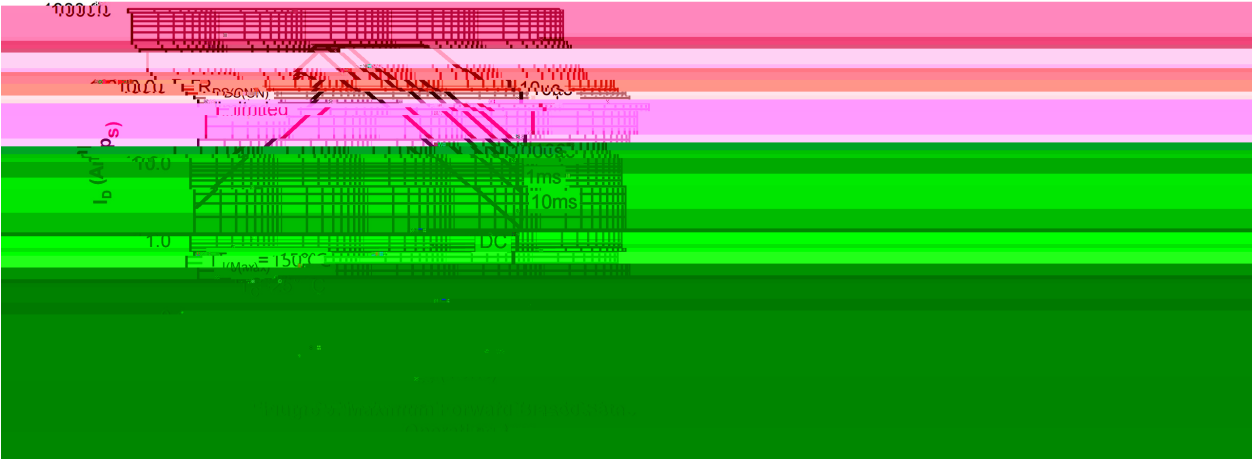
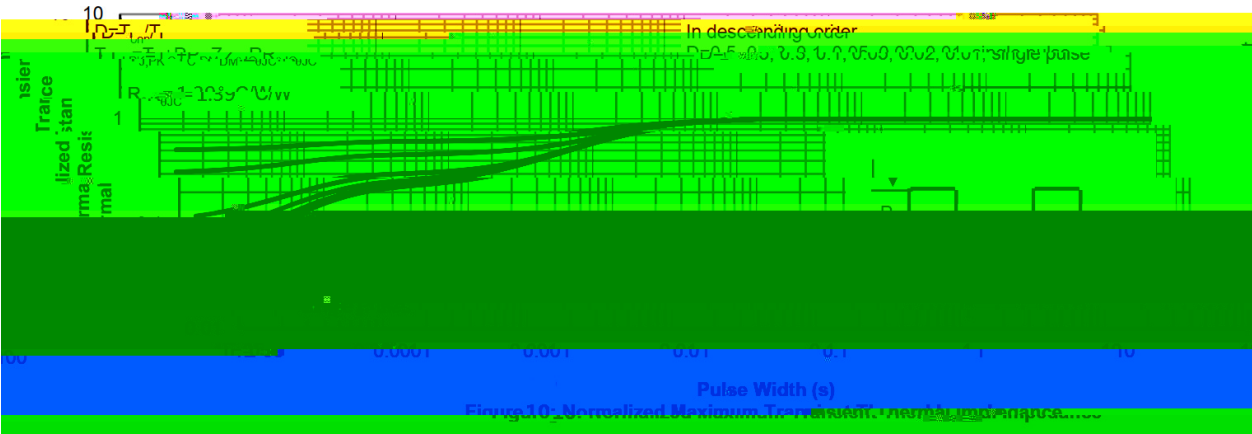
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	t _{d(on)}	V _{GS} =10V V _{DS} =20V R _L =1Ω R _{GEN} =3Ω		13		ns
Turn-On Rise Time	t _r			4		
Turn-Off Delay Time	t _{d(off)}			47		
Turn-Off Fall Time	t _f			6.5		

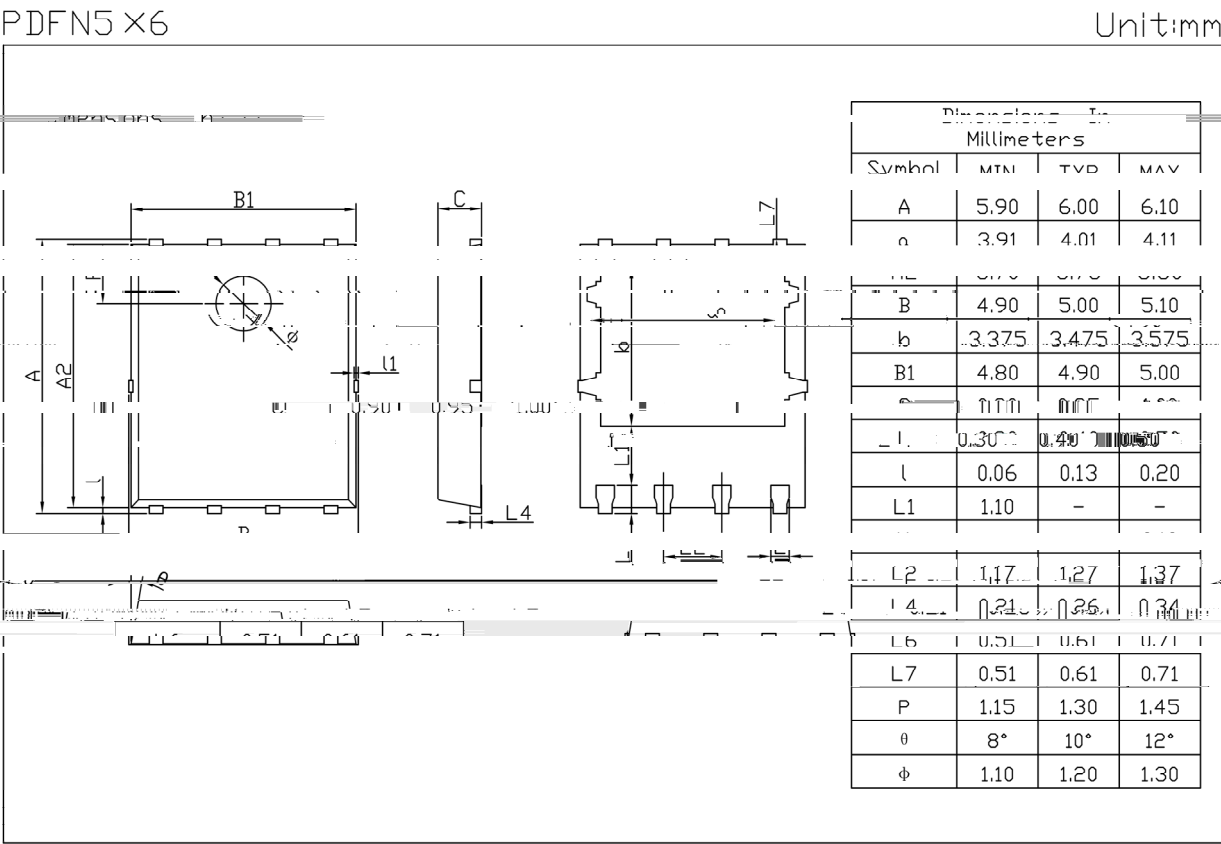
/ Electrical Characteristic Curve



/ Electrical Characteristic Curve



/ Package Dimensions



Rev.01 202209

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Rev.B Dec.-2024

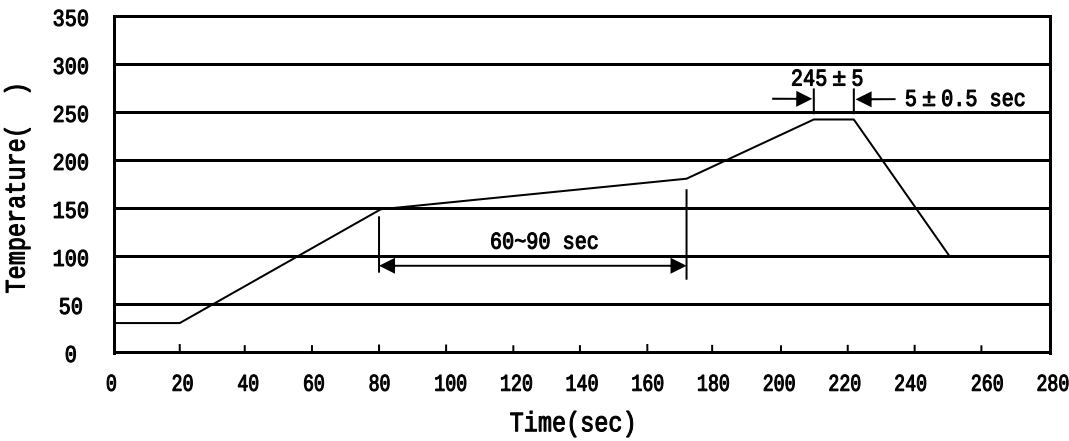


蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

/ Marking Instructions

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



注意

1. 预加热: 150℃~180℃, 时间: 60~90sec;
2. 峰值温度: 245℃±5℃, 持续时间: 5±0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

1. Preheating: 150~180 °C, Time: 60~90sec.
2. Peak Temp.: 245 °C ± 5 °C, Duration: 5 ± 0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

温度: 260℃±5 时间: 10±1 sec. Temp.: 260±5 Time: 10±1 sec

/ Packaging SPEC.

包装形式 / REEL

Package Type 封装形式	Units					Dimension (unit mm ³)		
	Units/Reel 每盘数量	Reels/Inner Box 盘数/内箱	Units/Inner Box 每内箱数量	Inner Boxes/Outer Box 内箱数/外箱	Units/Outer Box 每外箱数量	Reel	Inner Box	Outer Box
PDFN5×6	5,000	2	10,000	6	60,000	13"×12	360×360×50	380×335×366

/ Notices